

Appl. No. 10/708,047
Amdt. dated July 12, 2006
Reply to Office action of April 24, 2006

REMARKS/ARGUMENTS

1. Claim amendments:

5 The claim is amended in an effort to place the application in condition for allowance. No new matter is entered.

Claim 45 is amended to correct the typographical error as the Examiner required. No new matter is entered. Reconsideration of claim 45 is politely requested.

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Claims 39, 40, 45, and 46 are amended to overcome Rejection of claims set forth on Page 2 of the abovementioned Office action. No new matter is entered. Consideration of this amendment is respectfully requested.

15 2. Rejection of claims 39, 43, and 45 under 35 U.S.C. 102(e) as being anticipated by Sugimoto et al. (US 6,645,783).

20 The amended claim 39 recites a light-emitting device with compound substrate comprising a compound substrate which comprises a high thermal conductive layer and a substrate disposed around the high thermal conductive layer; a metal layer formed on the compound substrate for enhancing an adhesion between the compound substrate and the light-emitting stack layer, and a light-emitting stack layer formed on the metal adhesive layer.

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It is noteworthy that the metal layer is a melted metal or alloy used to provide an adhesion between the compound substrate and the light-emitting

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stack layer. Those skilled in the art will easily realize that the melted metal or alloy functions as an adhesive member and therefore is used to enhance an adhesion between the compound substrate and the light-emitting stack layer in the present application. However, Sugimoto's die bounding paste 7 used to attached the LED chip 2 to the radiator plate 3 is a silver paste which is low in the thermal conductivity (column 11, lines 6-7 and 62-63). It is well-known that the silver paste is a mixture of epoxy and silver powder. The die bonding paste 7 therefore provides an adhesion function by the epoxy and a reflection function by the silver powder. In addition, Sugimoto has never taught replacing the die bonding paste 7 with metal adhesive layer. Therefore the applicant asserts that the present application is patentably distinct from Sugimoto. Reconsideration of claim 39 is respectfully requested.

Claims 43 and 45 depends on claim 39 and should be allowed if claim 39 is allowed. Reconsideration of claims 43 and 45 is politely requested.

3. Objections to the claims:

Claims 40-42, 44, and 46 depends on claim 39 and should be allowed if claim 39 is allowed. Reconsideration of claims 40-42, 44, and 46 is politely requested.

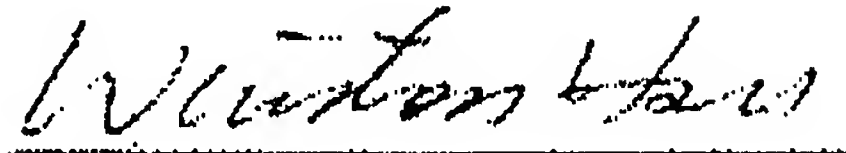
4. Allowed claims:

Allowance of claims 1, 3, 4, 8-12, 15-17, 19-21, and 25-38 is acknowledged and appreciated.

Applicant respectfully requests that a timely Notice of Allowance be issued in this case.

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Sincerely yours,



Date: July 12, 2006

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